

A Symposium on High-Performance Chips



**Stanford University,
Palo Alto, California**
August 22-24, 2004

CALL FOR CONTRIBUTIONS

For the last 15 years, Hot Chips has been the leading conference on high-performance microprocessors and related integrated circuits. The conference is held once a year in August on the Stanford University campus in the center of the world's electronics capital, Silicon Valley. The emphasis this year, as in previous years, is on real products and realizable technology. Topics of interest for this year's conference include but are not limited to:

- **Microprocessors**
- **Systems-on-chip**
- **Embedded processors**
- **Digital signal processors**
- **Application-specific processors**
- **Network/security processors**
- **Graphics/Multimedia/Game processors**
- **Communication/networking chips**
- **Wireless LAN/Wireless WAN chips**
- **Novel chips: quantum computing, microarray**
- **Low-power chips/Dynamic Power Management**
- **Reconfigurable chips/processors**
- **Reliability and design for test**
- **Compiler technology**
- **Operating system/chip interaction**
- **Advanced semiconductor process technology**
- **Advanced packaging technology**
- **Performance evaluation**

Presentations at HOT Chips are in the form of 30-minute talks. Presentation slides will be published in the HOT Chips Proceedings. Participants are not required to submit written papers, but a select group will be invited to submit a paper for inclusion in a special issue of IEEE Micro.

Submissions must consist of a title, extended abstract (two pages maximum), and the presenter's contact information (name, affiliation, job title, address, phone, fax, and email). Please indicate whether you have submitted, intend to submit, or have already presented or published a similar or overlapping submission to another conference or journal. Also indicate if you would like the submission to be held confidential; we do our best to maintain confidentiality.

Submissions are evaluated by the Program Committee on the basis of the performance of the device (or devices), degree of innovation, use of advanced technology, potential market significance, and anticipated interest to the audience. Research and software contributions will be evaluated with similar criteria. Authors will be notified of the status of their submission by the end of April, 2004.

Don't miss this chance to present your work to an audience of engineers, computer architects, and computer system and device researchers. Submissions must be received no later than **March 15, 2004**.

Please make your submissions in plain ascii text (in the message, not as an attachment) to:

hotchips-submission@cva.stanford.edu

(Submissions containing figures may be submitted in pdf, but plain ascii is preferred.)

For more information, see the Hot Chips 16 Web site at: **<http://www.hotchips.org>**

Send questions to

hotchips@cva.stanford.edu

or contact the co-program chairs:

Prof. Bill Dally at **hotchips@cva.stanford.edu**, or
Keith Diefendorff at **keithd@mac.com**

Sponsored by the Technical Committee on Microprocessors and Microcomputers of the IEEE Computer Society



Program Committee Co-Chairs
Prof. Bill Dally, Stanford University
Keith Diefendorff, MemoryLogix



Check the HOT CHIPS 16 web page for updates: <http://www.hotchips.org>



The Institute of
Electrical and
Electronics
Engineers, Inc.

540 University Ave. #150
Palo Alto, CA 94301

Call for
Papers

First Class
U.S. Postage
PAID
AID Mailing
Los Altos, CA
#229

HOT
C H I P S 16

August 22-24, 2004 Stanford University

For additional information, visit our web page: <http://www.hotchips.org>